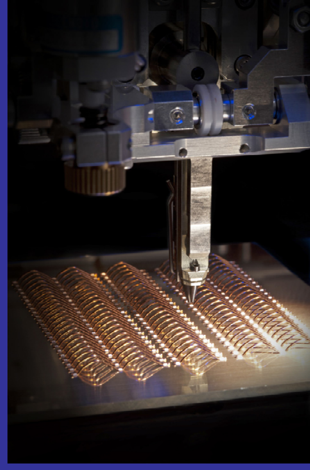
ULTRASONIC ROTARY HEAD BONDER

REBO-9W

ULTRASONIC ENGINEERING CO., LTD

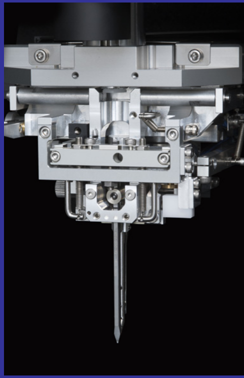
REBOSeries NEW model available

Cu Wire bonding
(φ200～500μm)

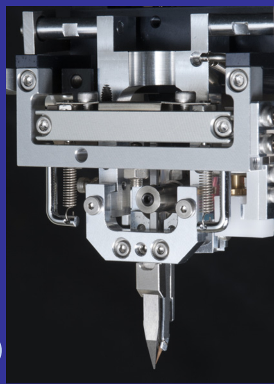


Ribbon bonding
(W:2mm, t:0.2mm)

Dual frequency transducer bonding head



Large wire
(Al φ100～500μm)



Medium wire
(φ75～150μm)

Small wire
(φ25～50μm)

High performance wire bonder

REBO-9W major specification

New digitally controlled generator

- Able to manage 80,110, 120kHz in 1 generator.
- Conversion to other type become easier.

Dual frequency transducer for Large wire

- 110kHz and 40kHz can be switched arbitrarily.

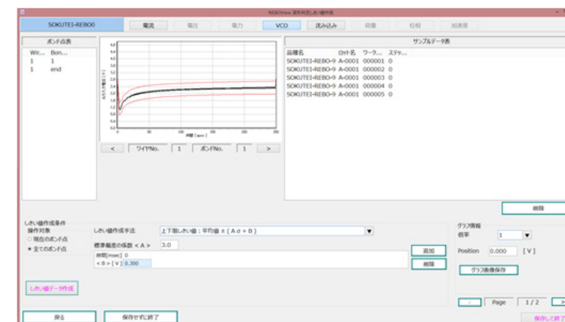
Optimum bonding suitable for junction point.

New controll system

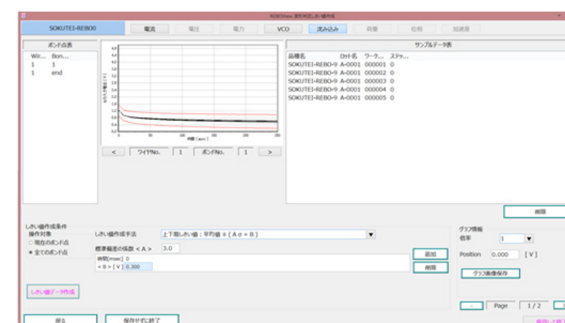
- Improved workability of maintenance.
- Touch-panel operation.
- SSD integrated for faster launch.

Current functions are available as well

Wave logging and judging function



VCO Waveform



SINK Waveform

Able to log 4 types of waveforms other than above as well.

Expansion of bonding area

- Expansion of bonding area to XY 300mm
- Available for a wide workpieces.

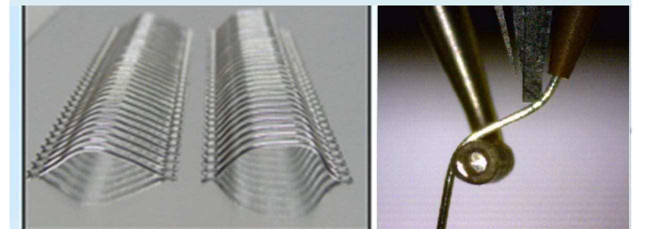
Auto-deformation check function (optional)

- Automatically measure and saves deformation data after bonding.

Loop former (optional)

Stable loop form under long span bonding.

・Loop control



Around tool observation

Able to confirm position and adjust tool, cutter ,and wire guide by monitor

MAJOR SPECIFICATION

Item	REBO-9W Series				
Wire	Small Wire	Medium Wire	Large Wire	Ribbon	Cu Wire
Wire/Ribbon size	25～50μm	75～150μm	100～500μm ※Till 600μm by option	W: 0.5mm～2.0mm t :0.1mm～0.3mm	200～500μm
Wire supply angle	45°	65°	75°	70°	75°
Wire cut method	Wire clamped Pull cut	Pull cut by XYZ axis movement	Motor driven cutter + XYZ axis movement combined		
Wire material	Aluminum				Copper
Ultrasonic frequency	120kHz	110kHz	110kHz / 110kHz/40kHz 40kHz for using 2 frequency	80kHz	
Bonding tool	Tools on market	Our original tool			
Bonding method	Ultrasonic wedge bonding				
Bonding area	X:300mm × Y:300mm Standard				
Z -stroke	80mm				
θ-stroke	460°				
Basic OS	Windows 8 ※				
Around tool observation	Able to manage position of tools and cutters by embedded camera pictures				
Wire program memory	10,000 bonding points /project				
Wave monitor logging	Transducer current & voltage, power, sink depth, phase, and voltage controlled oscillation. ＊VCO is not available for small wire.				
Pin less pull tester	Not available		Available	Not available	
Data making support	Offline data making software REBOndWin				
Product size	Approx. 710(W)×1225(D)×1630(H)mm（Signal tower and other projectiles not included)				
Mass weight	Approx. 620kg				
Power source	Three phase 200V～240V　50/60Hz				
Pneumatic source	0.49MPa				
Body color	Munsell　N9.0（Gloss)				

※ Windows is a registered trademark of united states Microsoft Corporation.

Caution: Please read operations manual carefully before using.

※The specification and other dimensions are subject to change without prior to notice for improvement.

http://www.cho-onpa.co.jp/　**Latest information available.**

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